



40V N-Channel Enhancement Mode MOSFET

Voltage

40 V

Current

136 A

Features

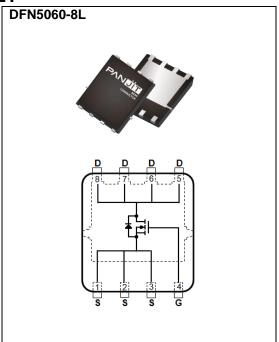
- RDS(ON), VGS@10V, ID@20A<3m Ω
- RDS(ON), VGS@7V, ID@20A<3.6mΩ
- Excellent FOM
- Standard Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: DFN5060-8L Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.08 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETE	SYMBOL	LIMIT	UNITS		
Drain-Source Voltage		V _{DS}	40	V	
Gate-Source Voltage		V _{GS}	±20	V	
Continuous Drain Current(Note 3)	T _C =25°C		136		
	T _C =100°C	l _D	96	Α	
Pulsed Drain Current(Note 1)	T _C =25°C	I _{DM}	544		
Power Dissipation	T _C =25°C	D-	100	10/	
	T _C =100°C	Po	50	W	
Continuous Drain Current(Note 4)	T _A =25°C		24.8	^	
	T _A =70°C	I _D	20.8	A	
Power Dissipation	T _A =25°C	Do	3.3	W	
	T _A =70°C	Po	2.3		
Single Pulse Avalanche Energy ^(Note 5)		Eas	240	mJ	
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55~175	°C	
Thermal Resistance ^(Note 4)	Junction to Case	R _{θJC}	1.5	°C/W	
	Junction to Ambient	$R_{\theta JA}$	45		





Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	40	-	-	<
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =50uA	2	2.8	3.5	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A	-	2.4	3	mΩ
		V _{GS} =7V, I _D =20A	-	2.8	3.6	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	-	-	1	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Dynamic ^(Note 6)						
Total Gate Charge	Qg	V _{DS} =32V, I _D =20A, V _{GS} =10V	-	43	-	nC
Gate-Source Charge	Qgs		-	13	-	
Gate-Drain Charge	Q_{gd}		-	11	-	
Input Capacitance	Ciss	V _{DS} =25V, V _{GS} =0V, f=1MHz	-	3050	-	pF
Output Capacitance	Coss		-	580	-	
Reverse Transfer Capacitance	Crss		-	77	-	
Gate resistance	Rg	f=1MHz	-	0.8	-	Ω
Turn-On Delay Time	td _(on)	V _{DS} =32V, I _D =20A, V _{GS} =10V, R _G =3Ω (Note 2)	-	17	-	ns
Turn-On Rise Time	tr		-	43	-	
Turn-Off Delay Time	td(off)		-	29	-	
Turn-Off Fall Time	tf		-	24	-	
Drain-Source Diode			_			
Diode Forward Current	Is	T _C =25°C	-	-	136	A
Pulsed Diode Forward Current	I _{SM}		-	-	544	
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V	-	0.8	1.3	V
Reverse Recovery Time	Trr	V _{GS} =0V, I _S =20A	_	40	-	ns
Reverse Recovery Charge	Qrr	dls/dt=100A/us	-	33	-	nC

NOTES:

- Pulse width≤100us, Duty cycle≤2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an $R_{\theta JC}$ =1.5°C/W, Pakage limited 100A.
- 4. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 5. The test condition is L=0.5mH, I_{AS}=31A, V_{DD}=30V, V_{GS}=10V, Starting T_J=25°C.
- 6. Guaranteed by design, not subject to production testing.





TYPICAL CHARACTERISTIC CURVES

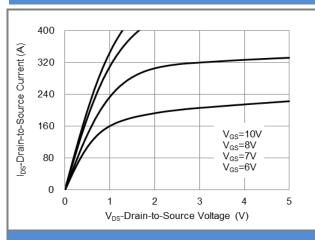


Fig.1 On-Region Characteristics

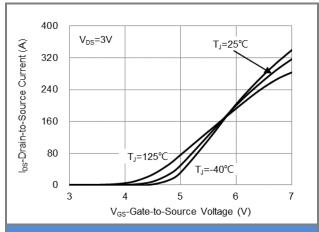


Fig.2 Transfer Characteristics

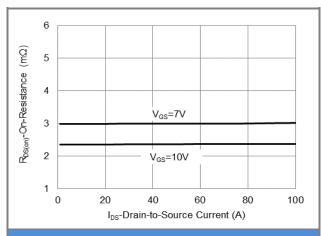


Fig.3 On-Resistance vs. Drain Current

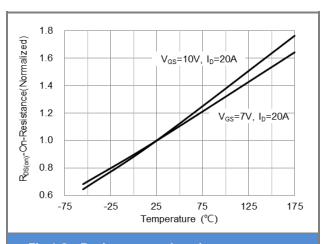
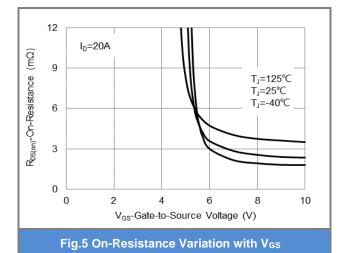


Fig.4 On-Resistance vs. Junction temperature



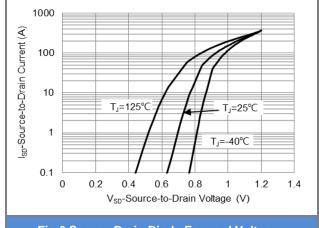


Fig.6 Source-Drain Diode Forward Voltage





TYPICAL CHARACTERISTIC CURVES

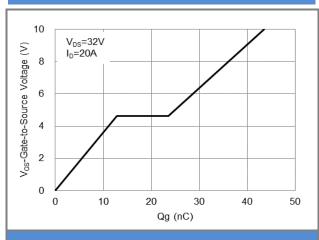


Fig.7 Gate-Charge Characteristics

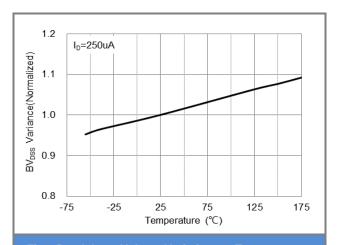


Fig.8 Breakdown Voltage Variation vs. Temperature

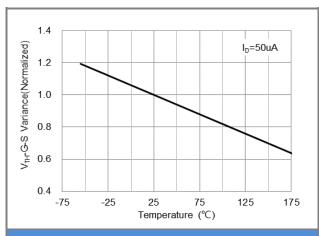


Fig.9 Threshold Voltage Variation with Temperature

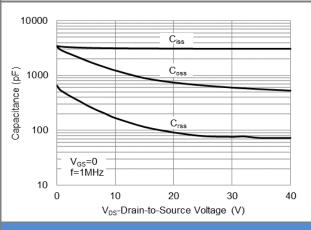
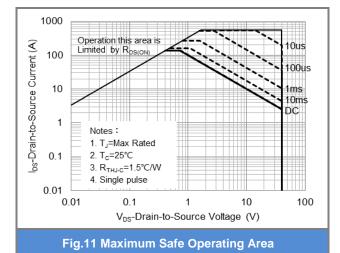


Fig.10 Capacitance vs. Drain-Source Voltage



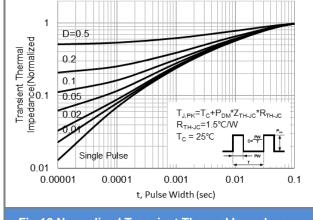


Fig.12 Normalized Transient Thermal Impedance

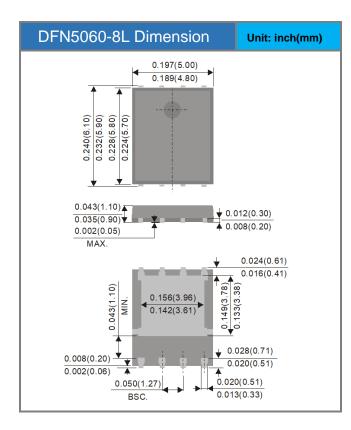


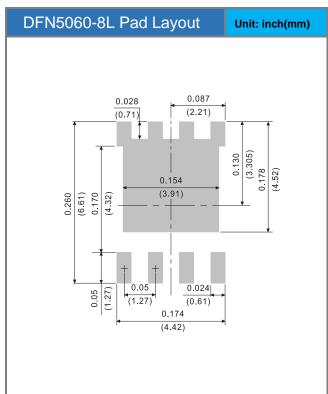


Part No. Packing Code Version

Part No. Packing Code	Package Type	Packing Type	Marking	Version
PJQ5542V-AU_R2_002A1	DFN5060-8L	3K pcs / 13" reel	Q5542V	Halogen free RoHS compliant

Packaging Information & Mounting Pad Layout









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